

HG60-00021-00 verification new HSN report

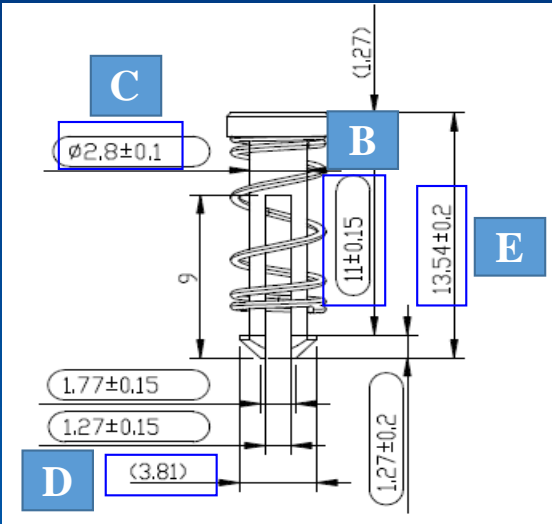
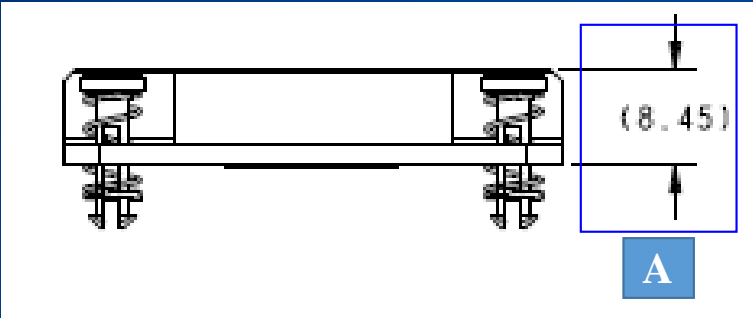
FOXCONN VN Team.

May.10th , 2023

Background

- **Purpose :** Change new HSN for ECO1004578 project :
 - + Model : BCM957412N4120DC
 - + Q'ty : 10pcs
 - + Vendor : Auras
 - + PN : HG60-00021-00 (Description : Assembly, Heat Sink, 65x40.74x8.45)
 - + Vendor : Auras

➤ **Measure dimension material review :**




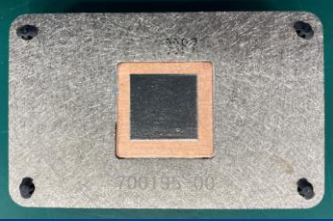

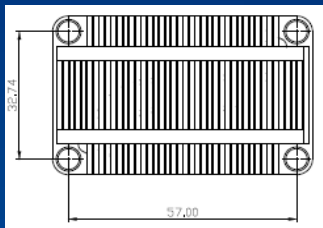
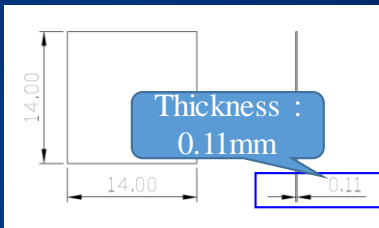
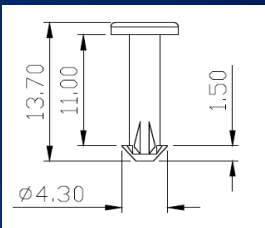
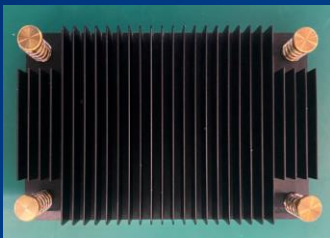
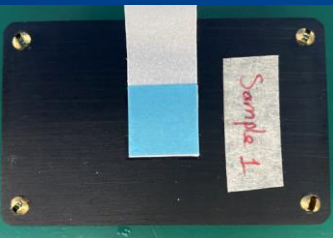

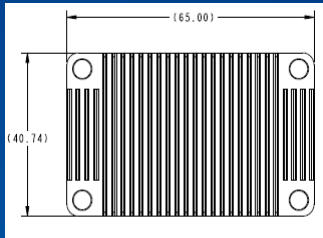
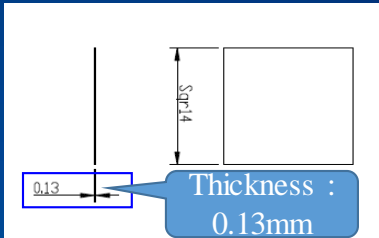
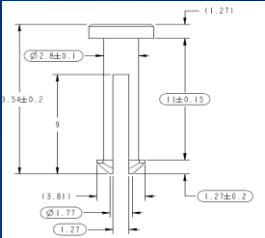
Unit: mm

Item	Drawing	Min spec	Max spec	#1	#2	#3	#4	#5	#6	#7	#8	#9	#10
A	8.45±0.1	8.35	8.55	8.40	8.38	8.38	8.37	8.38	8.38	8.39	8.40	8.37	8.40
B	11 ± 0.15	10.85	11.15	10.92	10.89	10.91	10.90	10.89	10.92	10.89	10.89	10.89	10.92
C	2.8±0.1	2.70	2.90	2.78	2.81	2.77	2.78	2.79	2.77	2.76	2.77	2.78	2.79
D	3.81 ± 0.1	3.71	3.91	3.75	3.78	3.82	3.80	3.79	3.80	3.81	3.76	3.77	3.79
E	13.54±0.2	13.34	13.74	13.65	13.60	13.57	13.59	13.61	13.64	13.59	13.58	13.58	13.56

- **Conclusion :** We checked the dimension of new HSN in spec.

Compare old HSN with new HSN

➤ Appearance compare:

Item	Actual Heatsink			Drawing Heatsink		
	Top side	Bot side	Push pin	Top side	TIM	Push pin
Old HSN			 Plastic		 Thickness : 0.11mm	
New HSN			 Copper		 Thickness : 0.13mm	

➤ Conclusion: - Appearance checked

1. Change design of push pin : - The material change from plastic to copper. The dimension as the same.
2. Change material of TIM : - The material change from T588 to T725. The new Tim have protect sheet cover & need remove before assembly .
3. Change design TOP side : - The fins old heatsink more than new heatsink.
4. Change design BOT side : - **The old HSN have copper and the new HSN haven't copper.**

Old HSN assembly review

➤ Picture review : (parameter setting : $0.2 \pm 0.02\text{mpa}$)



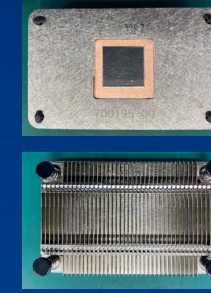
Fixture



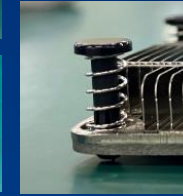
Place PCBA



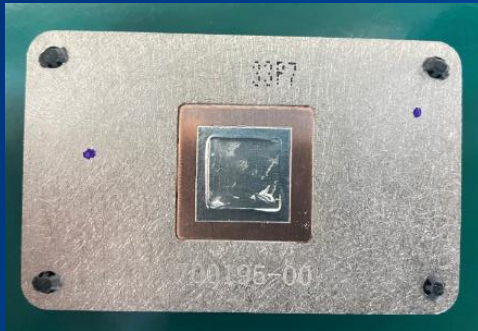
Place cover



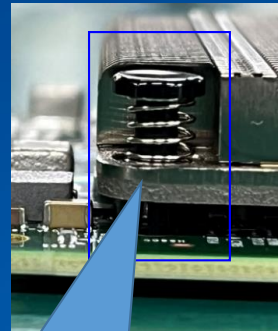
VI HSN



Place HSN



Disassembly HSN check TIM contact with BGA good



Check push pin don't shift after assembly



#1



#2



#4

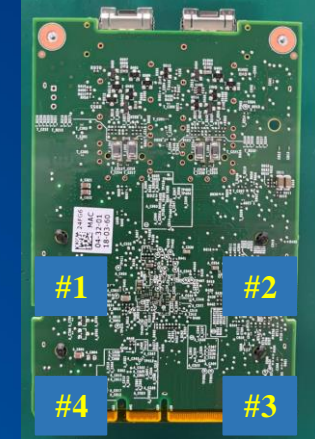


#3

Assembly OK



VI check after HSN



#1

#2

#4

#3

New HSN assembly review

➤ Picture review : (parameter setting : $0.2 \pm 0.02\text{mpa}$)



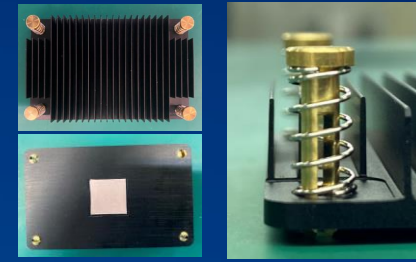
Fixture



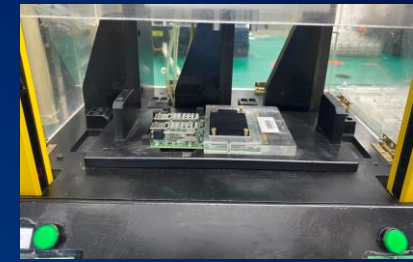
Place PCBA



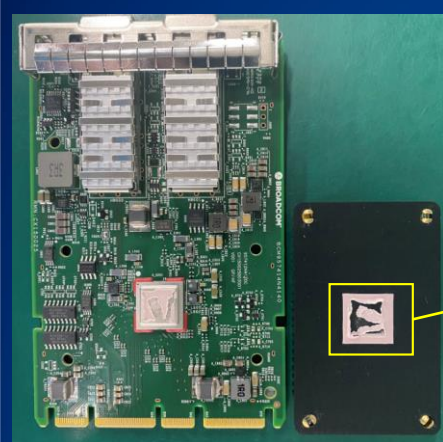
Place cover



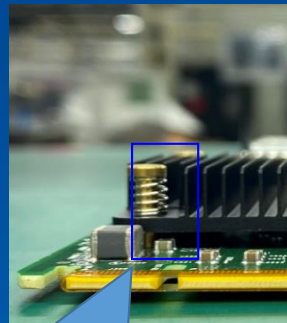
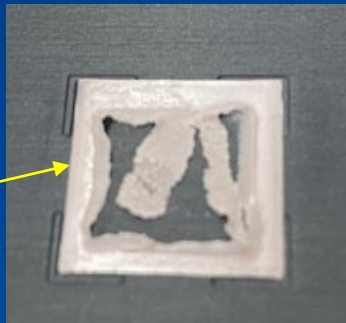
VI HSN



Place HSN



Disassembly HSN check TIM
contact with BGA good



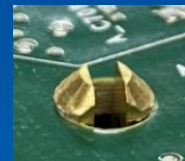
Check push pin don't
shift after assembly



#1



#2



#4

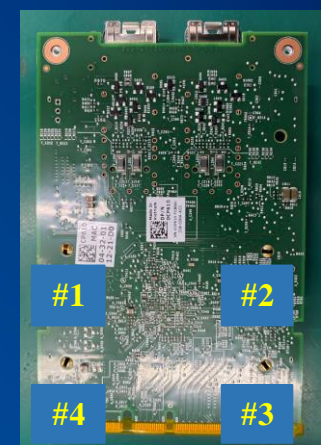


#3

Assembly OK



VI check after HSN



➤ Conclusion :

1. The structure of new HSN was change ,but the dimension are the same . So Can assembly as normal old HSN ,no detect any issue.
2. The Tim contact with BGA good.
3. The new Tim material will peel of after remove, So can't recycle HSN if need rework.

Thank you